

## AMENDMENTS TO THE CLAIMS

1. **(Currently amended)** A resin for a photoresist composition, ~~having a first structural unit that comprises a hydroxyl group bonded to a carbon atom, wherein the first structural unit comprises~~ comprising a  $\text{-CR}^1\text{R}^2\text{OH}$  group only at a terminal of a principal chain of the resin, wherein  $\text{R}^1$  and  $\text{R}^2$  each represent, independently, an alkyl group, halogen atom, or halogenated alkyl group, and at least one of  $\text{R}^1$  and  $\text{R}^2$  is an electron attractive group selected from the group consisting of halogen atoms and halogenated alkyl groups, ~~wherein said  $\text{-CR}^1\text{R}^2\text{OH}$  group is bonded at a principal chain terminal of a polymer of said resin.~~

2. **(Canceled).**

3. **(Original)** A resin for a photoresist composition according to claim 1, wherein said electron attractive group is a fluorine atom or a fluorinated alkyl group.

4. **(Previously presented)** A resin for a photoresist composition according to claim 1, wherein a proportion of the first structural unit comprising said  $\text{-CR}^1\text{R}^2\text{OH}$  group is at least 1 mol%, relative to a combined 100 mol% of all structural units other than said first structural unit within said resin for a photoresist composition.

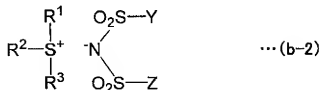
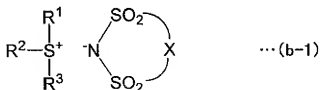
5. **(Canceled)**

6. **(Canceled)**

7. **(Previously presented)** A resin for a photoresist composition according to claim 1, further comprising an acid dissociable, dissolution inhibiting group.

8. **(Original)** A resin for a photoresist composition according to claim 7, further comprising (a1) a structural unit derived from a (meth)acrylate ester having an acid dissociable, dissolution inhibiting group, and (a2) a structural unit derived from a (meth)acrylate ester having a lactone ring.

9. **(Original)** A resin for a photoresist composition according to claim 8, further comprising (a3) a structural unit derived from a (meth)acrylate ester having a hydroxyl group.
10. **(Previously presented)** A resin for a photoresist composition according to claim 1, with a weight average molecular weight of no more than 12,000.
11. **(Previously presented)** A photoresist composition, comprising a resin for a photoresist composition according to claim 1.
12. **(Original)** A photoresist composition according to claim 11, further comprising an acid generator as a component (B).
13. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.
14. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), a sulfonium compound represented by either of general formulas (b-1) and (b-2) shown below:



wherein, X represents an alkylene group of 2 to 6 carbon atoms in which at least one hydrogen atom has been substituted with a fluorine atom; Y and Z each represent, independently, an alkyl group of 1 to 10 carbon atoms in which at least one hydrogen atom has been substituted with a

fluorine atom;  $R^1$  to  $R^3$  each represent, independently, an aryl group or an alkyl group, and at least one of  $R^1$  to  $R^3$  is an aryl group.

15. **(Original)** A photoresist composition according to claim 14, further comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.

16. **(Original)** A photoresist composition according to claim 11, further comprising a nitrogen-containing organic compound.

17. **(Previously presented)** A method for forming a resist pattern, using a photoresist composition according to claim 11, comprising the steps of:

applying the photoresist composition to a surface of a substrate;  
performing selective exposure through a desired mask pattern; and  
performing developing to form a resist pattern.

18. **(Previously presented)** A resin for a photoresist composition according to claim 1, wherein a proportion of the first structural units constituting said resin is 1-5 mol%, relative to a combined 100 mol% of all structural units other than said first structural units within said resin.

19. **(Previously presented)** A resin for a photoresist composition according to claim 1, wherein the first structural unit which includes the carbon atom in the  $\alpha$ -position of said hydroxyl group having at least one electron attractive group is substantively bonded only to the polymer terminal.

20. **(Previously presented)** A resin for a photoresist composition according to claim 5, wherein a proportion of the first structural units which have the substituents with a pKa value between 6 and 12 constituting said resin is 1-5 mol% relative to a combined 100 mol% of all structural units other than said first structural units within said resin.

21. **(Previously presented)** A resin for a photoresist composition according to claim 5, wherein the substituents with a pKa value between 6 and 12 are substantively bonded only to the polymer terminal.
22. **(New)** The resin for a photoresist composition according to claim 1, wherein a -S-(CH<sub>2</sub>)<sub>m</sub>-C(CF<sub>3</sub>)<sub>2</sub>-OH group is introduced at a terminal of a principal chain of the resin, wherein m represents an integer from 2 to 4.
23. **(New)** A resin for a photoresist composition, comprising: a -CR<sup>1</sup>R<sup>2</sup>OH group which is introduced at a terminal of a principal chain of the resin; and a structural unit derived from a (meth)acrylate ester containing an acid dissociable, dissolution inhibiting group, wherein R<sup>1</sup> and R<sup>2</sup> each represent, independently, an alkyl group, a halogen atom, or a halogenated alkyl group, and at least one of R<sup>1</sup> and R<sup>2</sup> is an electron attractive group selected from the group consisting of halogen atoms and halogenated alkyl groups.
24. **(New)** The resin for a photoresist composition according to claim 23, wherein a -S-(CH<sub>2</sub>)<sub>m</sub>-C(CF<sub>3</sub>)<sub>2</sub>-OH group is introduced at a terminal of a principal chain of the resin, wherein m represents an integer from 2 to 4.